

# **30V N-Channel Trench MOSFET**

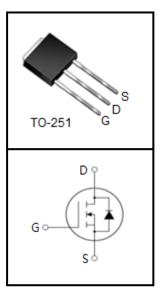
#### **FEATURES**

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Hard switched and high frequency circuits





Device Marking and Package Information				
Device	Package	Marking		
CTU03N8P5	TO-251	CTU03N8P5		

Absolute Maximum Ratings at T <sub>j</sub> = 25°C unless otherwise noted					
Parameter		Symbol	Value	Unit	
Drain-Source Voltage (V <sub>GS</sub> = 0V)		V <sub>DSS</sub>	30	V	
Continuous Drain Current T <sub>C</sub> = 25°C	(note1)	l <sub>D</sub>	60	А	
Continuous Drain Current T <sub>C</sub> = 100°C	(note1)		40	А	
Pulsed Drain Current	(note2)	I <sub>DM</sub>	120	А	
Gate Source Voltage		V <sub>GSS</sub>	±20	V	
Single Pulse Avalanche Energy	(note3)	E <sub>AS</sub>	57.8	mJ	
Power Dissipation	(note4)	P <sub>D</sub>	41	W	
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	-55~+175	°C	

Thermal Characteristics					
Parameter		Symbol	Value	Unit	
Thermal Resistance, Junction-Case	(note1)	$R_{ heta JC}$	3.6	°C/W	
Thermal Resistance, Junction-Ambient	(note1)	$R_{\theta JA}$	62		



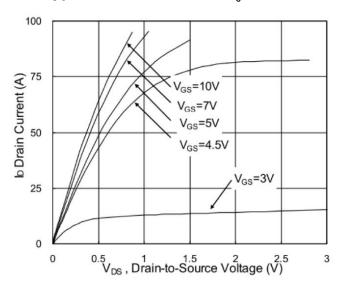
Parameter	Symbol		Value			
		Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 24V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	uA
		$V_{DS} = 24V, V_{GS} = 0V, T_{J} = 55^{\circ}C$		-	5	uA
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20V$		-	±100	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2	-	2.5	V
Drain-Source On-Resistance (note3)	R <sub>DS(on)</sub>	$V_{GS} = 10V, I_D = 30A$		7.3	8.5	mΩ
		$V_{GS} = 4.5V, I_{D} = 15A$		11	14	mΩ
Dynamic						
Input Capacitance	$C_iss$	$V_{GS} = 0V,$ $V_{DS} = 15V,$		1317	1843	pF
Output Capacitance	C <sub>oss</sub>			163	228	
Reverse Transfer Capacitance	$C_{rss}$	f = 1.0MHz		131	183	
Total Gate Charge	$Q_g$			12.6	17.6	nC
Gate-Source Charge	$Q_gs$	$V_{DD} = 15V, I_{D} = 15A,$ $V_{GS} = 4.5V$		4.2	5.9	
Gate-Drain Charge	$Q_{gd}$			5.1	7.1	
Turn-on Delay Time	$t_{d(on)}$			4.6	9.2	
Turn-on Rise Time	t <sub>r</sub>	V <sub>DS</sub> = 15V, I <sub>D</sub> = 15A		12.2	22	ns
Turn-off Delay Time	$t_{\text{d(off)}}$	$V_{GS} = 10V, R_G = 3.3\Omega$		26.6	53	
Turn-off Fall Time	t <sub>f</sub>			8	16	
Body Diode Characteristics						
Continuous Body Diode Current	I <sub>S</sub>	T 0-20			60	А
Pulsed Diode Forward Current	I <sub>SM</sub>	$T_C = 25^{\circ}C$			120	
Body Diode Voltage	$V_{SD}$	$T_J = 25^{\circ}C$ , $I_{SD} = 30A$ , $V_{GS} = 0V$			1.2	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 30A		9.2		ns
Reverse Recovery Charge	Q <sub>rr</sub>	di <sub>F</sub> /dt = 100A/μs		2.0		nC

#### **Notes**

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width  $\!\leq\!300 us$  , duty cycle  $\!\leq\!2\%$
- 3. The EAS data shows Max. rating . The test condition is VDD =25V,VGS =10V,L=0.1mH  $\,$
- 4. The power dissipation is limited by 175°C junction temperature
- 5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.



# **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted



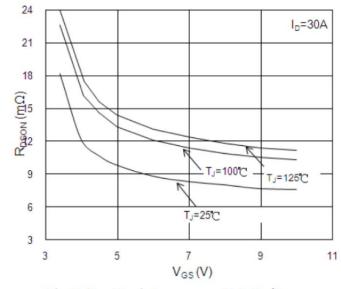


Fig.1 Typical Output Characteristics

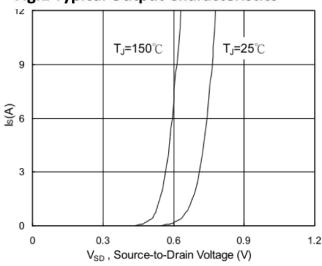


Fig.2 On-Resistance vs. G-S Voltage

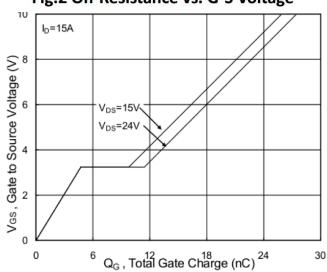
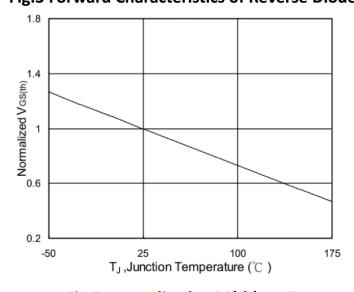


Fig.4 Gate-Charge Characteristics

Fig.3 Forward Characteristics of Reverse Diode



Normalized On Resistance

Fig.5 Normalized V GS(th) vs. T J

Fig.6 Normalized R DSON vs. T J

 $T_J$ , Junction Temperature ( $^{\circ}$ C)

1.8

0.2

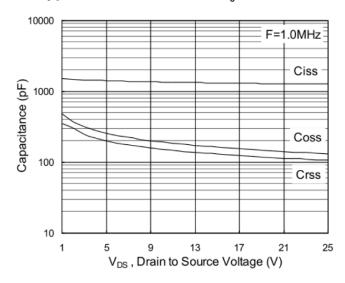
-50

175

130



# **Typical Characteristics** $T_J = 25$ °C, unless otherwise noted



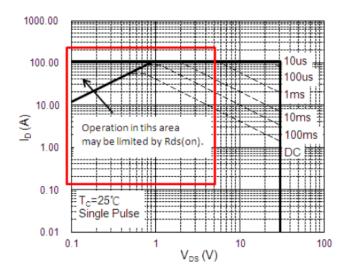


Fig.7 Capacitance

Fig.8 Safe Operating Area

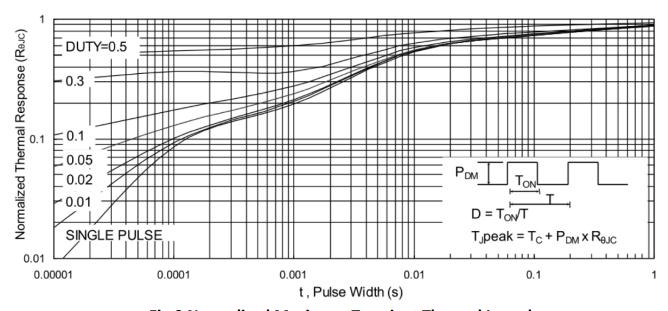


Fig.9 Normalized Maximum Transient Thermal Impedance



Figure A: Gate Charge Test Circuit and Waveform

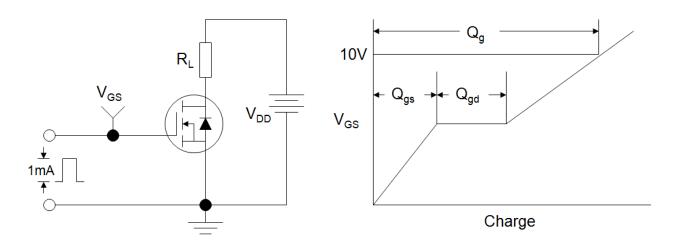


Figure B: Resistive Switching Test Circuit and Waveform

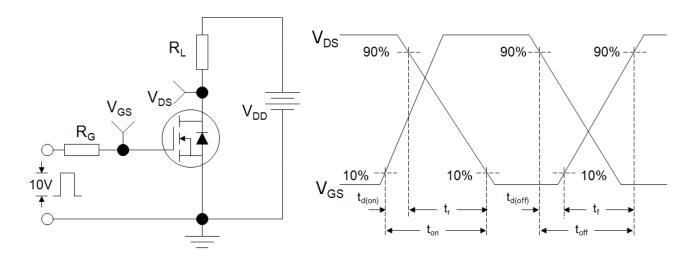
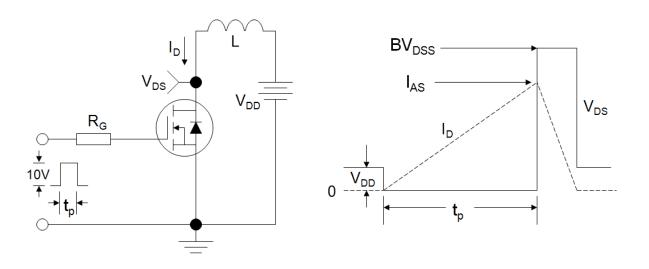
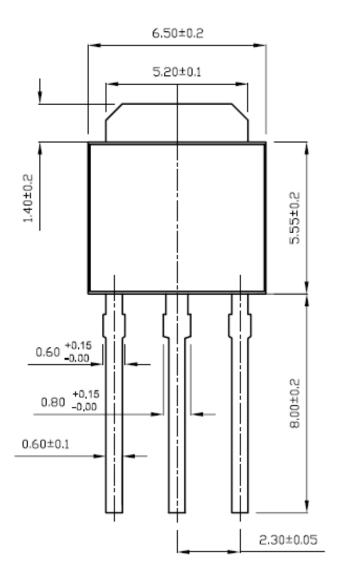


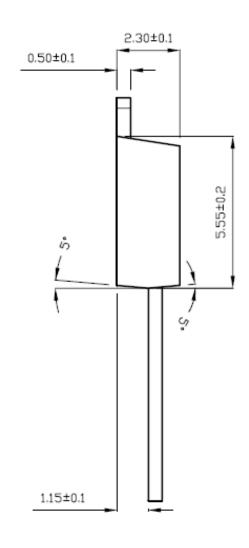
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





# TO-251







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